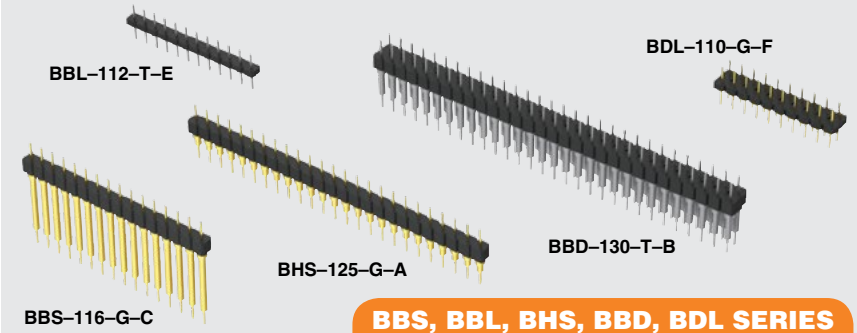
samtec



(2.54 mm) .100"

BBS, BBL, BHS, BBD, BDL SERIES

MACHINED BOARD STACKING STRIPS

Mates with:
SS, SD, HSS, SL, SDL, ESS, ESD

FEATURES

- Low-profile design achieves (3.89 mm) .153" board spacings when mated with SL Series.
- Approach the reliability of a permanent connection with the flexibility of a separable connection.

SPECIFICATIONS

For complete specifications see www.samtec.com?BBS, www.samtec.com?BBL, www.samtec.com?BHS www.samtec.com?BBD or www.samtec.com?BDL

Insulator Material:
Black Glass Filled Polyester (BBS, BBD, BBL)
Black High Temp Nylon (BDL)
Black Liquid Crystal Polymer (BHS)
Temperature Range:
-55 °C to +125 °C
Terminal Material:
Phosphor Bronze or Brass
Plating:
Au or Sn over 50 µ" (1.27 µm) Ni
RoHS Compliant:
Yes
Lead-Free Solderable:
Wave only (BBS, BBD, BBL, BDL)
Wave, or reflow with all Au (BHS)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

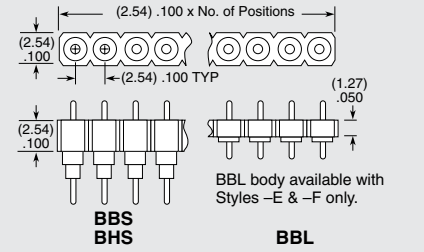
Note: Some lengths, styles and options are non-standard, non-returnable.

TYPE STRIP – **1** **NO. PINS PER ROW** – **PLATING OPTION** – **LEAD STYLE**

BBS = Standard Single Row

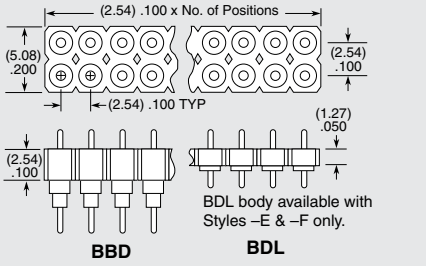
BBL = Low-Profile Single Row

BHS = High Temp Single Row



BBD = Standard Double Row

BDL = Low-Profile Double Row



–G =20 µ" (0.51 µm) Gold

–T =Tin

01 thru 32 =BBS & BBL

01 thru 36 =BBD, BDL & BHS

–A Z = (5.33 mm) .210"

–B Z = (8.51 mm) .335"

–C Z = (14.86 mm) .585"

–E Z = (1.78 mm) .070"

–F Z = (2.16 mm) .085"

